

ABSTRACT

The circuit board of the present invention comprises base film 11 that is a base layer, first conductive circuit 13 manufactured by hardening conductive paste material formed in a predetermined shape on the base film 11, first insulating layer 15 manufactured by hardening insulating paste material formed on the base film 11 including the first conductive circuit 13, and second conductive circuit 19 manufactured by hardening conductive paste material in a predetermined shape on the first insulating layer 15, wherein electronic part 4 built-in by the first insulating layer 15 and second insulating layer 17 is connected to the second conductive circuit 19, and the first conductive circuit 13 is connected to the second conductive circuit 19 through a via. Accordingly, it is possible to make a multilayer circuit structure at relatively low temperatures and to realize a circuit board which is reduced in thickness and has flexibility with use of inexpensive plastic film.

[Selected drawing] Fig. 10